# **Specification of Thermoelectric Module**

TEC1-19914

# **Description**

The 199 couples, 40 mm × 40 mm size single module which is made of our high performance ingot to achieve superior cooling performance and 70 °C or larger delta T max, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

### **Features**

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

# **Application**

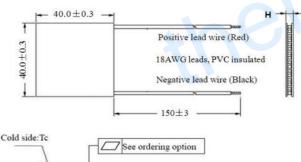
- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

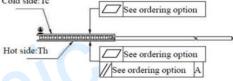
# **Performance Specification Sheet**

Th (°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>	
DT <sub>max</sub> (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U <sub>max</sub> (Voltage)	25.0	26.9	Voltage applied to the module at DT <sub>max</sub>	
I <sub>max</sub> (Amps)	12.6	12.6	DC current through the modules at DT <sub>max</sub>	
Q <sub>Cmax</sub> (Watts)	197.8	216.1	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance (Ohms)	1.53	1.68	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

# Geometric Characteristics Dimensions in millimeters

# **Manufacturing Options**





### A. Solder:

\_\_\_\_\_\_

B. Sealant:

1. T100: BiSn (Tmelt=138°C)

1. NS: No sealing (Standard)

2. T200: CuAgSn (Tmelt = 217°C)

2. SS: Silicone sealant

3. T240: SbSn (Tmelt =  $240^{\circ}$ C)

3. EPS: Epoxy sealant

### C. Ceramics:

# **D. Ceramics Surface Options:**

1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)

1. Blank ceramics (not metalized)

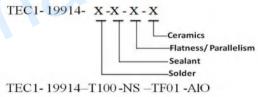
2. Aluminum Nitride (AlN)

2. Metalized

# **Ordering Option**

Configura	Thickness	Flatness/	Lead wire length (mm)		
Suffix	H / (mm)	Parallelism (mm)	Standard/Optional length		
TF	0:3.3±0.1	0:0.08/0.08	150±3/Specify		
TF	1:3.3±0.03	1:0.03/0.03	150±3/Specify		
Fg. TF01: Thickness 3.3±0.1(mm) and Flatness 0.03/0.03(mm)					

# Naming for the Module



T100: BiSn(Tmelt=138°C)

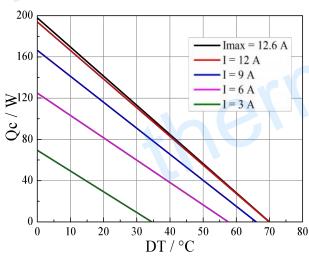
NS: No sealing AIO: Alumina, white 96% TF01: Thickness  $\pm$  0.1 (mm) and Flatness/Parallelism 0.025/0.025 (mm)

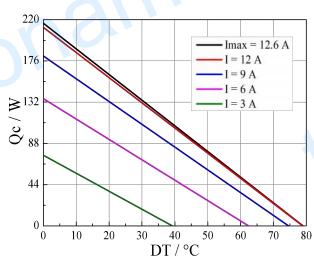
# **Specification of Thermoelectric Module**

# **TEC1-19914**

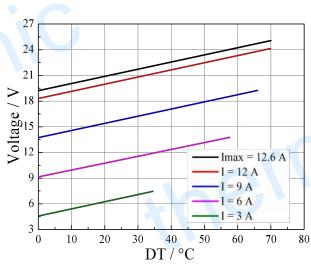
# Performance Curves at Th=27 °C

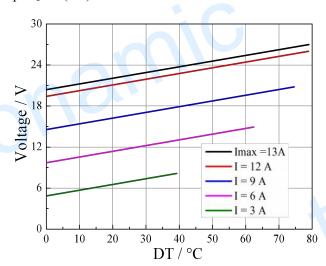
# Performance Curves at Th=50 °C



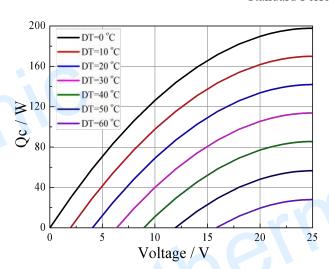


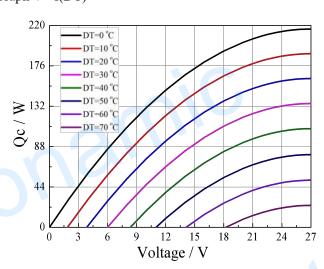
Standard Performance Graph Qc= f(DT)





Standard Performance Graph V= f(DT)





Standard Performance Graph Qc = f(V)

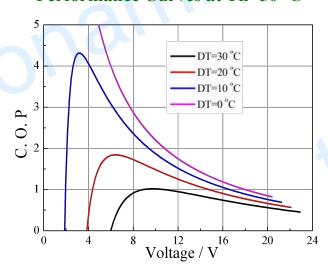
# **Specification of Thermoelectric Module**

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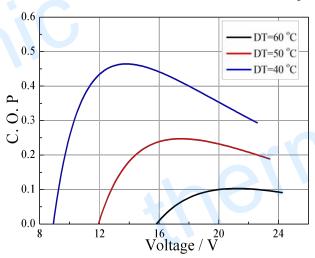
# Performance Curves at Th=27 °C

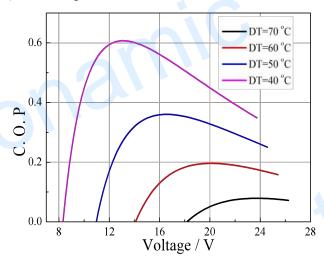
# 5 4 DT=30 °C DT=20 °C DT=10 °C DT=0 °C DT=0 °C DT=0 °C

# Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

# **Operation Cautions**

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating.
- $\bullet$  Operation below  $I_{\text{max}}$  or  $V_{\text{max}}$
- Work under DC